Declaration and Power of Attorney For Patent Application English Language Declaration

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As a below named inventor,	I hereby declare that:		
My residence, post office ac	ddress and citizenship a	are as stated below next t	to my name,
I believe I am the original, fi first and joint inventor (if plu and for which a patent is so SEMICONDUCTOR DEVICE	iral names are listed be ught on the invention e	elow) of the subject matte entitled	.
the specification of which is	attached hereto unles	s the following box is che	cked:
was filed on	as		•
		rnational Application Num	ber
and was amended on	(if applicable).		
thereby state that I have re specification, including the c			
ER § 1.56.	isclose information wh	ich is material to patentab	pility as defined in 37
hereby claim foreign prior application(s) for patent or in which designated at least of dentified below by checking applicational application of the control	nventor's certificate, on ne country other than g the box, any foreign	or § 365(a) of any PCT In the United States, listed application for patent or before that of the applica	ternational application below and have also inventor's certificate, ation on which priority
Prior Foreign Application(s) Pat. Appln. Hei 9-293,046	JAPAN	24 October, 1997	Priority Not Claimed
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(Number) (Country	(1)	(Day/Month/Year Filed)	L
(Number) (Country	· /)	(Day/Month/Year Filed)	
I hereby claim the benefit un listed below.	der 35 U.S.C. § 119(e) of any United States pro	ovisional application(s)
Application Number)	(Filing Date)		
(Application Number)	(Filing Date)		·
I hereby claim the benefit un any PCT International applic subject matter of each of th or PCT International applicat I acknowledge the duty to d CFR § 1.56 which became national or PCT international	ation designating the less of this application in the manner proving isclose information whe available between the	United States, listed below ation is not disclosed in the ided by the first paragraph sich is material to patenta the filing date of the prio	w and, insofar as the he prior United States n of 35 U.S.C. § 112, bility as defined in 37

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(Application Number	r)	(Fillng Date)	(Status - pat	ented, pending, abandoned)	
(Application Number	r)	(Filling Date)	(Status - pat	ented, pending, abandoned)	
POWER OF AT agent(s) to pros	secute this app	named inventor, I lication and transac	hereby appoir at all business i	nt the following attorne in the Patent and Trader	ay(s) and/or mark Office
Paul F. Prestia Allan Ratner Andrew L. Ney Kenneth N. Nigon Kevin R. Casey Benjamin E. Leace James C. Simmons	Reg.No. 23,031 Reg.No. 19,717 Reg.No. 20,300 Reg.No. 31,549 Reg.No. 32,117 Reg.No. 33,412 Reg.No. 24,842	Lawrence E, Ashery Robert L. Anderson Christopher R. Lewis Louis W. Beardell, Jr. Rocco L. Adomato Jacques L. Etkowicz Eric A. Dichter	Reg.No. 34,515 Reg.No. 25,771 Reg.No. 35,201 Reg.No. 40,506 Reg.No. 40,480 Reg.No. 41,738 Reg.No. 41,708		eg.No. 36,593 eg.No. 42,480 -
Address all corre		an Wastlebas Danier	- DO Day 000	V II	
Address all telepi	hone calls to:	at (610) 407-07	<u>n, P.O. Box 980</u> 00.	, Valley Forge, PA 19482	<u>!-0980</u>
hereby declar	e that all sta	atements made her	rein of my ow	n knowledge are true a	lle tedt bas
				be true; and further	
nade are punis United States (application or ar	hable by fine Code and that ny patent issue	or imprisonment, o such willful false d thereon.	or both, under statements m	se statements and the Section 1001 of Title ay jeopardize the valid	18 of the
ul⊨#ame of sole or f	first inventor (given	name, family name) Yuj	I JODAI		
nventor's signature Residence Uji-shi,	Kyoto IAPAN	yryn Jud	<u>·</u>	Date October 1	5, 1998
Stizenship JAPAN	-			·	
		Nakamori, Uji-shi, Ł	Cyoto 611-0021	JAPAN	
ull name of second j	oint inventor, if any	(given name, family nam	e)		
econd Inventor's sign	nature			Date	ĺ
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Additional inve	ntors are b ing nam	ted on separately number	ed sheets attached	hereto.	İ

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